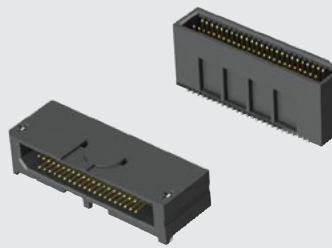
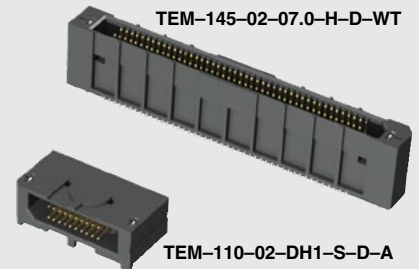




TEMS-125-02-03.0-H-D



TEM-145-02-07.0-H-D-WT



TEM-120-02-DH1-S-D-A

TEM-110-02-DH1-S-D-A

(0.80 mm) .0315"

TEM, TEMS, TEM-DH SERIES

MICRO TIGER EYE™ HEADER

TEM, TEM-DH Mates with:

SEM, SEML

TEMS Mates with:

SEMS

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?TEM or www.samtec.com?TEMS

Insulator Material:

Black Liquid Crystal Polymer

Terminal Material:

Phosphor Bronze

Plating:

Au or Sn over

50 μm (1.27 μm) Ni

Current Rating:

2.9 A per pin

(2 pins powered)

Voltage Rating:

235 VAC/330 VDC

Operating Temp Range:

-55 °C to +125 °C

RoHS Compliant:

Yes

PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



FILE NO. E11594

OTHER SOLUTIONS

- Latching option: See TEM-L1 in Discrete Wire Cable section.
- Board Stacking: See SFM, TFM Series
- Cable Assemblies: See SFSD, TFSD, SESDT Series

ALSO AVAILABLE (MOQ Required)

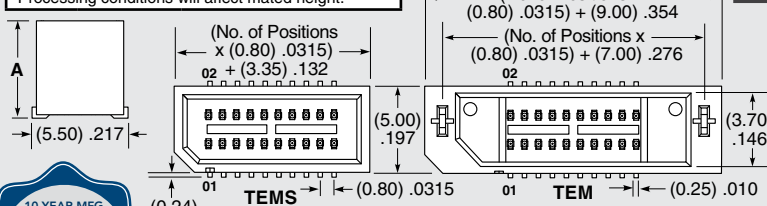
- Other sizes
- Other platings

Note: Some sizes, styles and options are non-standard, non-returnable.

TYPE STRIP	1	NO. OF POSITIONS	02	STACK HEIGHT	PLATING OPTION	D	OPTION	OTHER OPTION
TEM = Tiger Eye™ Strip		05, 10, 15, 20, 25 (Per Row)		-03.0 = 6 mm Stack Height	-FG = Gold Flash		-A = Alignment Pin (Not available with -LC or -WT)	-K = (5.50 mm) .217" DIA Polyimide film Pick & Place Pad (Required for TEMS)
TEMS = Tiger Eye™ Slim Strip		30, 35, 40, 45, 50 (Per Row) (TEM only) (Standard sizes)		-04.0 = 7 mm Stack Height	-G = 10 μm (0.25 μm) Gold on contact, Gold Flash on tail		-LC = Locking Clip (Not available with -A or -WT) (Manual placement required)	-TR = Tape & Reel (Required for TEMS)
				-07.0 = 10 mm Stack Height	-H = 30 μm (0.76 μm) Gold on contact, Gold Flash on tail		-WT = Weld Tab (Not available with -A or -LC)	

STACK HEIGHT	A	MATED HEIGHT* (WHEN MATED WITH SEM/SEMS)
-03.0	(6.610) .2209	6 mm
-04.0	(6.610) .2602	7 mm
-07.0	(9.610) .3783	10 mm

*Processing conditions will affect mated height.



HIGH-SPEED CHANNEL PERFORMANCE

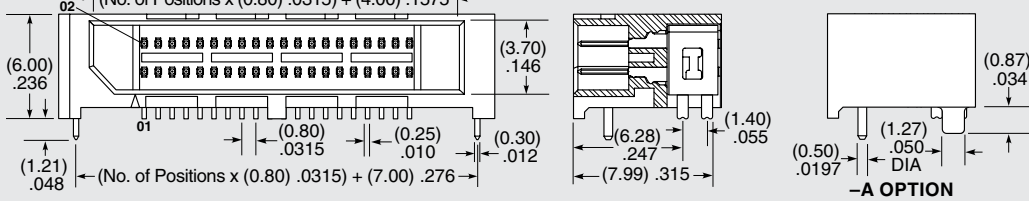
Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

8
Gbps

POWER/SIGNAL APPLICATION



TEM	1	NO. OF POSITIONS	02	DH1	PLATING OPTION	D	OPTION
		10, 15, 20, 25, 30, 35, 40, 45, 50 (Per Row) (Standard sizes)			-F = Gold Flash on contact, Matte Tin on tail		-A = Alignment Pin
					-L = 10 μm (0.25 μm) Gold on contact, Matte Tin on tail		
					-S = 30 μm (0.76 μm) Gold on contact, Matte Tin on tail		



Due to technical progress, all designs, specifications and components are subject to change without notice.